

WHAT IS CLAIMED IS:

1. An apparatus for reading a mark on a wafer, comprising:
a support structure having a mark reading side and a wafer support side;
means for illuminating said wafer; and
means for reflecting light from said wafer.
- 5 2. The apparatus of claim 1, wherein said mark reading side is a vertically oriented side and said wafer support side is positioned at an angle and contains at least one slot.
3. The apparatus of claim 2, wherein said at least one slot comprises a plurality of
10 slots, each slot of said plurality of slots is spaced apart from an adjacent slot by at least a width of said wafer.
4. The apparatus of claim 1, wherein said mark is a scribe mark.
- 15 5. The apparatus of claim 1, wherein said means for illuminating comprises one of a light emitting diode or ambient light.
6. The apparatus of claim 1, wherein said means for reflecting light comprises a mirror material disposed on a surface of said wafer support side.
- 20 7. The apparatus of claim 6, wherein said means for reflecting light comprises a mirror spaced apart from the mirror material.
8. The apparatus of claim 7, wherein said mirror is a concave mirror.
- 25 9. An apparatus for reading a scribe mark on a wafer, said apparatus having no movable parts comprising:
a body having first and second plates, said first plate having at least one slot formed therein; and
30 a reflective material formed on a portion of said first plate.

10. The apparatus of claim 9, further including a vertical support, wherein said vertical support couples said first plate to said second plate.

11. The apparatus of claim 9, wherein said reflective material is a mirror material.

12. The apparatus of claim 9, further including a mirror optically coupled to said mirror material.

13. The apparatus of claim 12, wherein said mirror is a concave mirror.

14. The apparatus of claim 9, further including a light source for providing light to be reflected to said mirror material.

15. The apparatus of claim 9, wherein said light source is a diode.

16. A method for reading a mark on a semiconductor wafer, comprising:
providing a semiconductor wafer having a scribe mark;
receiving light reflected from the scribe mark; and
reflecting the light reflected from the scribe mark to a scribe mark reading area.

17. The method of claim 16, further including providing a source of light, wherein the light illuminates the semiconductor wafer.

18. The method of claim 16, wherein reflecting the light includes rectifying an image within the light.

19. The method of claim 16, further including viewing the scribe marks on a plurality of wafers simultaneously.

20. The method of claim 16, further including using a camera to record images of the scribe marks.